



BAP64LX

Silicon PIN diode

Rev. 5 — 12 May 2015

Product data sheet

1. Product profile

1.1 General description

Planar PIN diode in a SOD882D leadless ultra small plastic SMD package.

1.2 Features and benefits

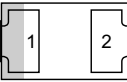

- High voltage, current controlled RF resistor for RF attenuators and switches
- Low diode capacitance
- Low forward resistance
- Very low series inductance
- For applications up to 3 GHz
- AEC-Q101 qualified

1.3 Applications

- RF attenuators and switches

2. Pinning information

Table 1. Discrete pinning

Pin	Description	Simplified outline	Symbol
1	cathode ^[1]	 Transparent top view	 <i>sym006</i>
2	anode		

[1] The marking bar indicates the cathode.

3. Ordering information

Table 2. Ordering information

Type number	Package		
	Name	Description	Version
BAP64LX	DFN1006D-2	leadless ultra small plastic package; 2 terminals; body 1 × 0.6 × 0.4 mm	SOD882D



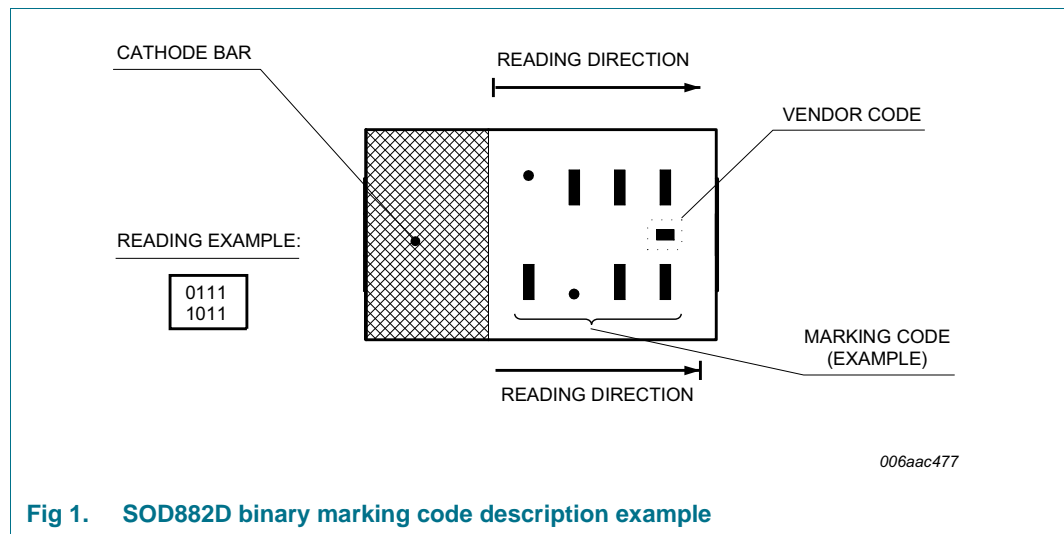
4. Marking

Table 3. Marking codes

Type number	Marking code ^[1]
BAP64LX	1111 1111

[1] For SOD882D binary marking code description, see [Figure 1](#).

4.1 Binary marking code description



5. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_R	reverse voltage		-	60	V
I_F	forward current		-	100	mA
P_{tot}	total power dissipation	$T_{sp} = 90\text{ °C}$	-	150	mW
T_{stg}	storage temperature		-65	+150	°C
T_j	junction temperature		-65	+150	°C

6. Thermal characteristics

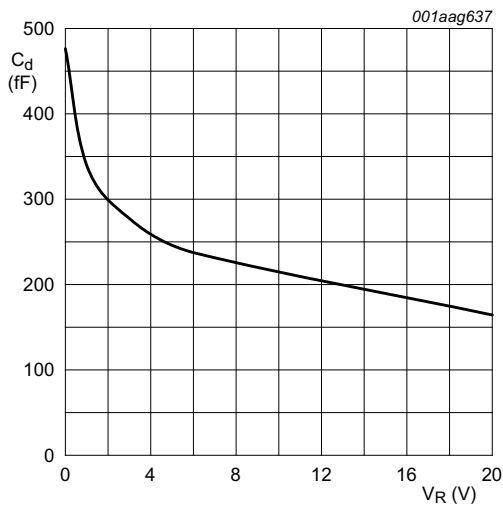
Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Typ	Unit
$R_{th(j-sp)}$	thermal resistance from junction to solder point		56	K/W

7. Characteristics

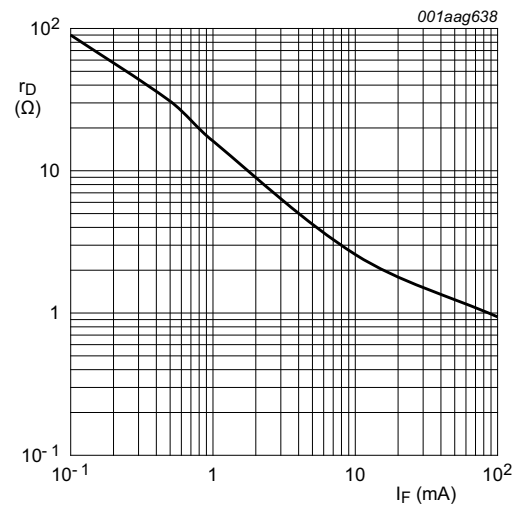
Table 6. Characteristics
T_{amb} = 25 °C unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V _F	forward voltage	I _F = 100 mA	-	0.95	1.1	V
I _R	reverse current	V _R = 100 V	-	-	100	nA
C _d	diode capacitance	see Figure 2 ; f = 1 MHz;				
		V _R = 0 V	-	0.48	-	pF
		V _R = 1 V	-	0.34	-	pF
		V _R = 20 V	-	0.17	0.30	pF
r _D	diode forward resistance	see Figure 3 ; f = 100 MHz;				
		I _F = 0.5 mA	-	31	50	Ω
		I _F = 1 mA	-	16	26	Ω
		I _F = 10 mA	-	2.6	4.4	Ω
		I _F = 100 mA	-	0.9	1.5	Ω
ISL	isolation	see Figure 4 ; V _R = 0 V;				
		f = 900 MHz	-	22	-	dB
		f = 1800 MHz	-	16	-	dB
		f = 2450 MHz	-	14	-	dB
L _{ins}	insertion loss	see Figure 5 ; I _F = 0.5 mA;				
		f = 900 MHz	-	1.22	-	dB
		f = 1800 MHz	-	1.21	-	dB
		f = 2450 MHz	-	1.22	-	dB
L _{ins}	insertion loss	see Figure 5 ; I _F = 1 mA;				
		f = 900 MHz	-	0.22	-	dB
		f = 1800 MHz	-	0.23	-	dB
		f = 2450 MHz	-	0.24	-	dB
L _{ins}	insertion loss	see Figure 5 ; I _F = 10 mA;				
		f = 900 MHz	-	0.12	-	dB
		f = 1800 MHz	-	0.14	-	dB
		f = 2450 MHz	-	0.15	-	dB
L _{ins}	insertion loss	see Figure 5 ; I _F = 100 mA;				
		f = 900 MHz	-	0.09	-	dB
		f = 1800 MHz	-	0.10	-	dB
		f = 2450 MHz	-	0.11	-	dB
τ _L	charge carrier life time	when switched from I _F = 10 mA to I _R = 6 mA; R _L = 100 Ω; measured at I _R = 3 mA	-	1.0	-	μs
L _S	series inductance	I _F = 100 mA; f = 100 MHz	-	0.4	-	nH



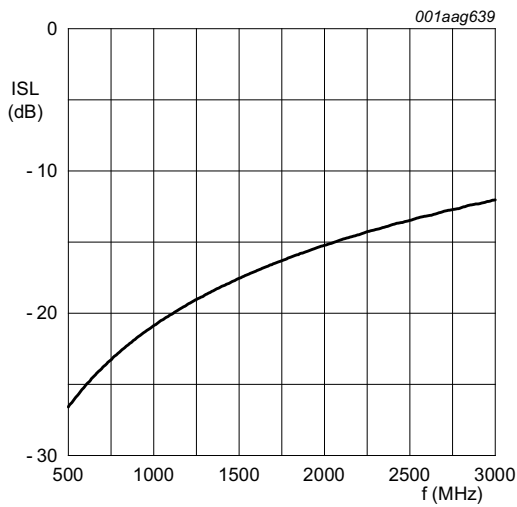
$f = 1 \text{ MHz}; T_j = 25 \text{ }^\circ\text{C}.$

Fig 2. Diode capacitance as a function of reverse voltage; typical values



$f = 100 \text{ MHz}; T_j = 25 \text{ }^\circ\text{C}.$

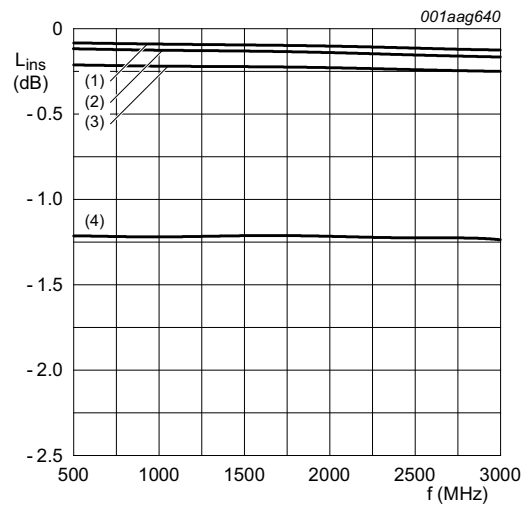
Fig 3. Forward resistance as a function of forward current; typical values



$T_{amb} = 25 \text{ }^\circ\text{C}$

Diode zero biased and inserted in series with a 50 Ω stripline circuit

Fig 4. Isolation of the diode as a function of frequency; typical values



$T_{amb} = 25 \text{ }^\circ\text{C}$

- (1) $I_F = 100 \text{ mA}$
- (2) $I_F = 10 \text{ mA}$
- (3) $I_F = 1 \text{ mA}$
- (4) $I_F = 0.5 \text{ mA}$

Diode inserted in series with a 50 Ω stripline circuit and biased via the analyzer Tee network

Fig 5. Insertion loss of the diode as a function of frequency; typical values

8. Package outline

DFN1006D-2: Leadless ultra small plastic package; 2 terminals; body 1 x 0.6 x 0.4 mm

SOD882D

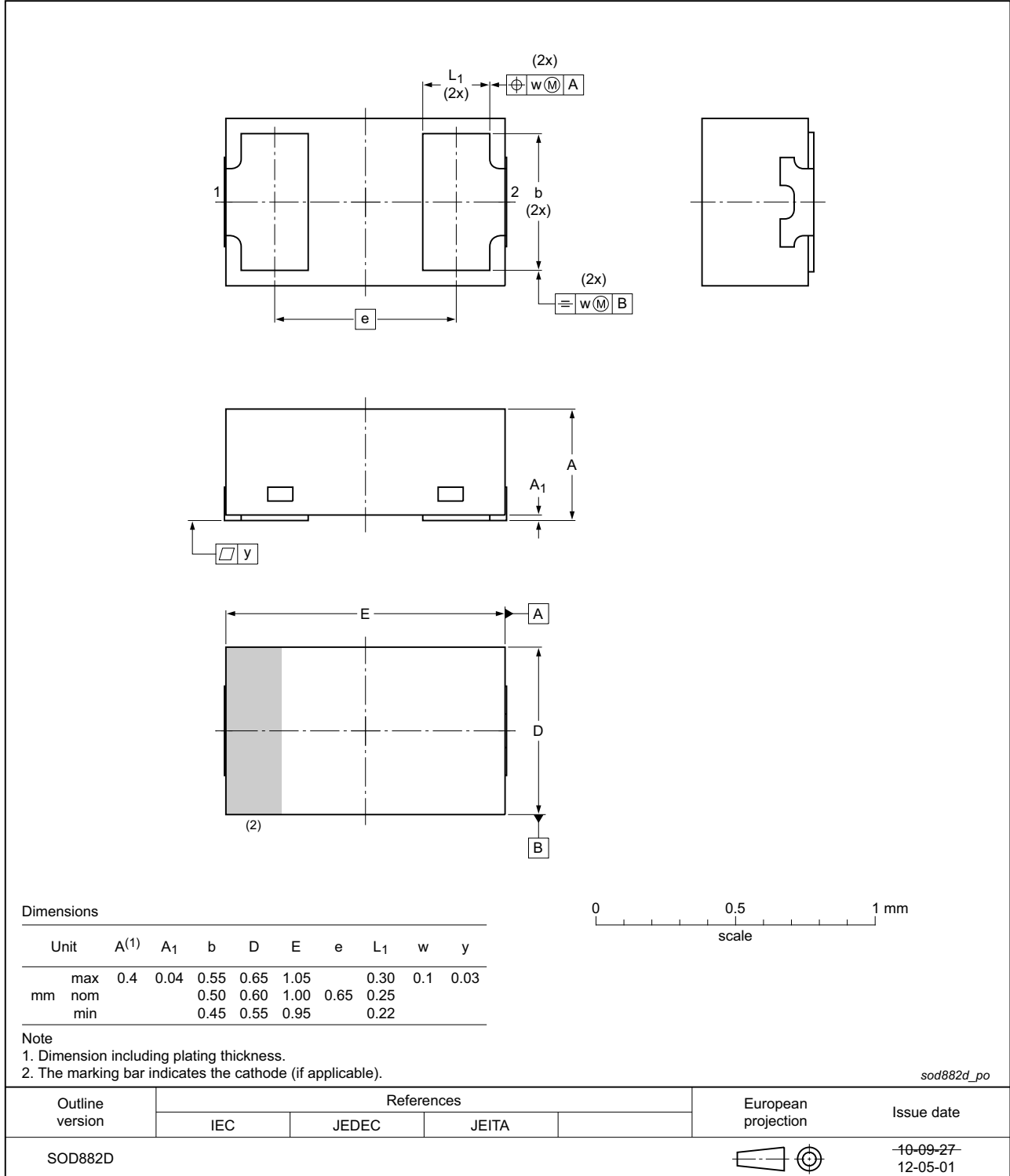


Fig 6. Package outline SOD882D (DFN1006D-2)

9. Abbreviations

Table 7. Abbreviations

Acronym	Description
AQL	Acceptable Quality Level
PIN	P-type, Intrinsic, N-type
SMD	Surface Mounted Device
S4	Special inspection level 4

10. Revision history

Table 8. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BAP64LX v.5	20150512	Product data sheet	-	BAP64LX v.4
Modifications:	• AEC-Q101 qualified			
BAP64LX v.4	20140416	Product data sheet	-	BAP64LX v.3
BAP64LX v.3	20140211	Product data sheet	-	BAP64LX v.2
BAP64LX v.2	20130807	Product data sheet	-	BAP64LX v.1
BAP64LX v.1	20070629	Product data sheet	-	-

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11.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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